

#### LECTURE 19

-BJT



#### Topics to be covered

• BJT

#### Transistors

- Two main categories of transistors:
  - bipolar junction transistors (BJTs) and
    field effect transistors (FETs).
- Transistors have 3 terminals where the application of current (BJT) or voltage (FET) to the input terminal increases the amount of charge in the active region.
- The physics of "transistor action" is quite different for the BJT and FET.
- In analog circuits, transistors are used in amplifiers and linear regulated power supplies.
- In digital circuits they function as electrical switches, including logic gates, random access memory (RAM), and microprocessors.

#### **Modern Transistors**



-

N

Ц

#### **BJT Fabrication**

- BJT can be made either as discrete devices or in planar integrated form.
- In discrete, the substrate can be used for one connection, typically the collector.
- In integrated version, all 3 contacts appear on the top surface.
  - The E-B diode is closer to the surface than the B-C junction because it is easier make the havier doping at the top.



- Early BJTs were fabricated using alloying an complicated and unreliable process.
- The structure contains two p-n diodes, one between the base and the emitter, and one between the base and the collector.

# BJT Structure - Plana *p*-base diffusion



The "**Planar Structure**" developed by Fairchild in the late 50s shaped the basic structure of the BJT, even up to the present day.





 In the planar process, all steps are performed from the surface of the wafer

#### BJTs are usually constructed vertically

Controlling depth of the emitter's n doping sets the base width



### **Advanced BJT Structures**

- The original BJT structure survived, practically unchanged, since the mid 60's.
- As the advances in MOS development appears, some of the fabrication technology are also applied to the BJT.
  - Low defect epitaxy
  - Ion implant
  - Plasma etching (dry etch)
  - LOCOS (local oxidation of Si)
  - Polysilicon layers
  - Improved lithography



#### **Isolation Methods**

- The most significant advances in reducing overall device size and packing density have come from improved isolation methods.
- The traditional junction isolation technique requires the p+ deep diffusion to be aligned to the n+ buried layer that is covered by a thick epitaxial layer.
- The area (and hence junction capacitance) is determined by alignment tolerance, area for side diffusion, and allowance for the spread of the depletion region.
- Modern isolation techniques: oxide isolation, and trench isolation.

## **Oxide & Trench Isolation**





- Oxide isolation processes were intorduced in the late 70's. They utilize wet anisotropic etch (KOH) of the <100> Si wafer with Si<sub>3</sub>N<sub>4</sub> as mask.
- The KOH etch will erode the <111> plane. Oxide is either deposited or grown to fill the V-grooves.
- The base and emitter are formed on the large mesa and the collector on the small mesa.
- To further reduce the area between adjacent mesa, trench isolation can be used, making use of trench etching.
- The trench is typically 2µm wide and 5µm deep. The trench walls are oxidized and the remaining volume is filled with polysilicon.

# The First Transistor: Point-contact

#### trancietor



A point-contact transistor was the first type of solid state electronic transistor ever constructed.

It was made by researchers
 John Bardeen & Walter
 Houser Brattain at Bell
 Laboratories in December
 1947.

First commercially available point-contact transistor

The point-contact transistor was commercialized and sold by Western Electric and others but was rather quickly superseded by the junction transistor.



### The Junction Transistor

- First BJT was invented early in 1948, only weeks after the point contact transistor.
- Initially known simply as the junction transistor.
- It did not become practical until the early 1950s.
- The term "bipolar" was tagged onto the name to distinguish the fact that both carrier types play important roles in the operation.
- Field Effect Transistors (FETs) are "unipolar" transistors since their operation depends primarily on a single carrier type.

# Bipolar Junction Transistors (BJT)

- A bipolar transistor essentially consists of a pair of PN Junction diodes that are joined back-to-back.
- There are therefore two kinds of BJT, the NPN and PNP varieties.
- The three layers of the sandwich are conventionally called the Collector, Base, and Emitter.

